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Voluntary, preliminary amendment

Claims

- 5 1. A method for producing a hybrid frame or hybrid housing, in which a leadframe with soldering and/or bonding tags after being placed in an injection moulding die is moulded with plastic to form a housing part of the hybrid frame or the hybrid housing, characterized in that the soldering and/or bonding tags of the leadframe are held down in the injection moulding die for the compensation of surface defects at least during a part of the injection moulding process by means of a stamp.
- 10 2. The method according to claim 1, characterized in that the stamp is a forming stamp.
3. The method according to claim 2, characterized in that the soldering and/or bonding tags are form-stamped during the moulding process.
- 15 4. The method according to claim 1, characterized in that a leadframe made from a plated strip is used.
- 20 5. A hybrid housing with a housing part and bonding tags of a leadframe projecting from the housing part, characterized in that at least one of the soldering and/or bonding tags has a form-stamping section, which can be acted upon by a stamp, and a holding section surrounding said form-stamping section.

6. A hybrid frame, characterized in that at least one of the soldering and/or bonding tags has a form-stamping section, which can be acted upon by a stamp, and a holding section surrounding said form-stamping section.

Claims

1. A method for producing a hybrid frame or hybrid housing, in which a leadframe with soldering and/or bonding tags (3a, 3b, 3c) after being placed in an injection moulding die is moulded with plastic to form a housing part (2) of the hybrid frame or the hybrid housing (1), characterized in that the soldering and/or bonding tags (3a-3c) of the leadframe are held down in the injection moulding die for the compensation of surface defects at least during a part of the injection moulding process by means of a stamp.
2. The method according to claim 1, characterized in that the stamp is a forming stamp.
3. The method according to claim 2, characterized in that the soldering and/or bonding tags (3a-3c) are form-stamped during the moulding process.
4. The method according to one of the preceding claims, characterized in that a leadframe (3) made from a plated strip is used.
5. A hybrid housing with a housing part (2) and bonding tags (3a-3c) of a leadframe (3) projecting from the housing part (2), characterized in that at least one of the soldering and/or bonding tags (3a-3c) has a form-stamping section (3a'-3c'), which can be acted upon by a stamp, and a holding section (3a''-3c'') surrounding said form-stamping section (3a'-3c').
6. A hybrid frame, characterized in that at least one of the soldering and/or bonding tags (3a-3c) has a form-stamping section (3a'-3c'), which can be

acted upon by a stamp, and a holding section (3a"-3c") surrounding said form-stamping section (3a'-3c').

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